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April 2015

H11AA1M, H11AA4M 6-Pin DIP AC Input Phototransistor Optocouplers

Features

- Bi-polar Emitter Input
- Built-in Reverse Polarity Input Protection
- Safety and Regulatory Approvals:
 - UL1577, 4,170 VAC_{RMS} for 1 Minute
 - DIN-EN/IEC60747-5-5, 850 V Peak Working Insulation Voltage

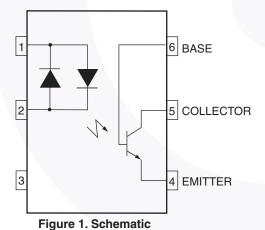
Applications

- AC Line Monitor
- Unknown Polarity DC Sensor
- Telephone Line Interface

Description

The H11AA1M and H11AA4M devices consist of two gallium-arsenide infrared emitting diodes connected in inverse parallel driving a single silicon phototransistor output.

Schematic



Package Outlines

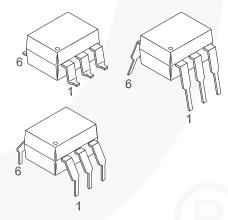


Figure 2. Package Outlines

Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter		Characteristics
Installation Classifications per DIN VDE	< 150 V _{RMS}	I–IV
0110/1.89 Table 1, For Rated Mains Voltage	< 300 V _{RMS}	I–IV
Climatic Classification		55/100/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
\/	Input-to-Output Test Voltage, Method A, $V_{IORM} \times 1.6 = V_{PR}$, Type and Sample Test with $t_m = 10$ s, Partial Discharge < 5 pC	1360	V _{peak}
V _{PR}	Input-to-Output Test Voltage, Method B, V _{IORM} x 1.875 = V _{PR} , 100% Production Test with t _m = 1 s, Partial Discharge < 5 pC	1594	V _{peak}
V _{IORM}	Maximum Working Insulation Voltage	850	V _{peak}
V _{IOTM}	Highest Allowable Over-Voltage	6000	V _{peak}
	External Creepage	≥ 7	mm
	External Clearance	≥ 7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
T _S	Case Temperature ⁽¹⁾	175	°C
I _{S,INPUT}	Input Current ⁽¹⁾	350	mA
P _{S,OUTPUT}	Output Power ⁽¹⁾	800	mW
R _{IO}	Insulation Resistance at T _S , V _{IO} = 500 V ⁽¹⁾	> 10 ⁹	Ω

Note:

1. Safety limit values – maximum values allowed in the event of a failure.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Unit
TOTAL DEVIC	E		
T _{STG}	Storage Temperature	-40 to +125	°C
T _{OPR}	Operating Temperature	-40 to +100	°C
TJ	Junction Temperature	-40 to +125	°C
T _{SOL}	Lead Solder Temperature	260 for 10 seconds	°C
D	Total Device Power Dissipation @ 25°C	270	mW
P_{D}	Derate Linearly From 25°C	2.94	mW/°C
EMITTER			
I _F	Continuous Forward Current	60	mA
I _F (pk)	Forward Current – Peak (1 µs pulse, 300 pps)	±1.0	Α
D	LED Power Dissipation @ 25°C	120	mW
P_{D}	Derate Linearly From 25°C	1.41	mW/°C
DETECTOR			
I _C	Continuous Collector Current	50	mA
P_{D}	Detector Power Dissipation @ 25°C	150	mW
	Derate linearity from 25°C	1.76	mW/°C

Electrical Characteristics

 $T_A = 25^{\circ}C$ Unless otherwise specified.

Individual Component Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
EMITTER				-		
V _F	Input Forward Voltage	I _F = ±10 mA		1.17	1.50	V
CJ	Capacitance	V _F = 0 V, f = 1.0 MHz		80		pF
DETECTO	R		•			
BV _{CEO}	Breakdown Voltage, Collector-to-Emitter	I _C = 1.0 mA, I _F = 0	30	100		V
BV _{CBO}	Breakdown Voltage, Collector-to-Base	$I_C = 100 \mu A, I_F = 0$	70	120		V
BV _{EBO}	Breakdown Voltage, Emitter-to-Base	$I_E = 100 \mu A, I_F = 0$	5	10		V
BV _{ECO}	Breakdown Voltage, Emitter-to-Collector	I _E = 100 μA, I _F = 0	7	10		V
I _{CEO}	Leakage Current, Collector-to-Emitter	V _{CE} = 10 V, I _F = 0		1	50	nA
C _{CE}	Capacitance Collector to Emitter	V _{CE} = 0, f = 1 MHz		10		pF
C _{CB}	Collector to Base	V _{CB} = 0, f = 1 MHz		80		pF
C _{EB}	Emitter to Base	V _{EB} = 0, f = 1 MHz		15		pF

Transfer Characteristics

Symbol	Characteristics	Test Conditions	Device	Min.	Тур.	Max.	Unit
CTR _{CF}	Current Transfer Ratio,	$I_F = \pm 10 \text{ mA}, V_{CE} = 10 \text{ V}$	H11AA1M	20			%
OTTICE	Collector-to-Emitter	1F - ±10 111/1, VCE - 10 V	H11AA4M	100			%
	Current Transfer Ratio, Symmetry	$I_F = \pm 10 \text{ mA}, V_{CE} = 10 \text{ V}$ (Figure 13)	All	0.33		3.00	
V _{CE(SAT)}	Saturation Voltage, Collector-to-Emitter	$I_F = \pm 10 \text{ mA}, I_{CE} = 0.5 \text{ mA}$	All			0.40	V

Isolation Characteristics

Symbol	Characteristic	Test Conditions	Min.	Тур.	Max.	Unit
V _{ISO}	Input-Output Isolation Voltage	t = 1 Minute	4170	<i>A</i>		VAC _{RMS}
C _{ISO} Isolation Capacitance		V _{I-O} = 0 V, f = 1 MHz		0.7		pF
R _{ISO}	Isolation Resistance	V _{I-O} = ±500 VDC, T _A = 25°C	10 ¹¹		/	Ω

Typical Performance Characteristics

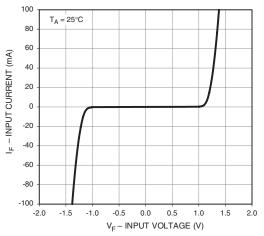


Figure 3. Input Voltage vs. Input Current

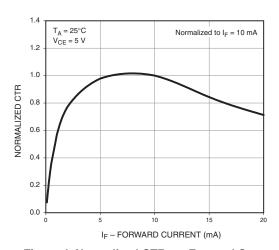


Figure 4. Normalized CTR vs. Forward Current

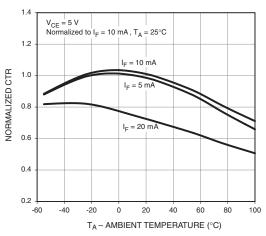


Figure 5. Normalized CTR vs. Ambient Temperature

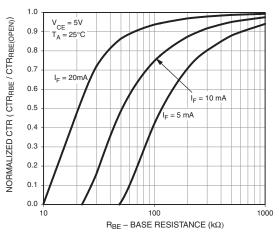


Figure 6. CTR vs. RBE (Unsaturated)

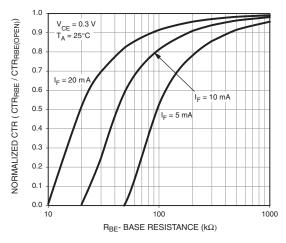


Figure 7. CTR vs. RBE (Saturated)

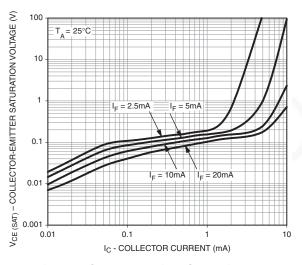


Figure 8. Collector-Emitter Saturation Voltage vs. Collector Current

Typical Performance Characteristics (Continued)

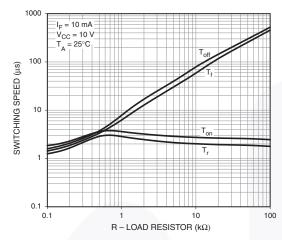


Figure 9. Switching Speed vs. Load Resistor

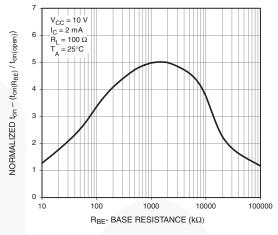


Figure 10. Normalized ton vs. RBE

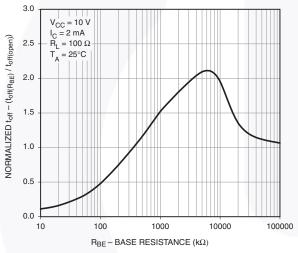


Figure 11. Normalized toff vs. RBE

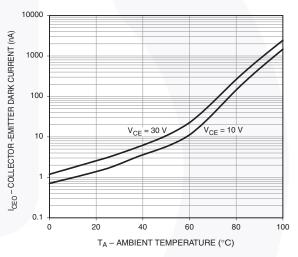


Figure 12. Dark Current vs. Ambient Temperature

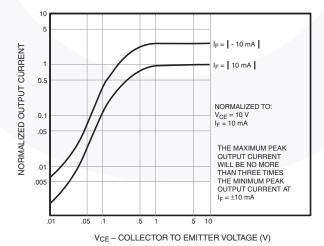


Figure 13. Output Symmetry Characteristics

Reflow Profile

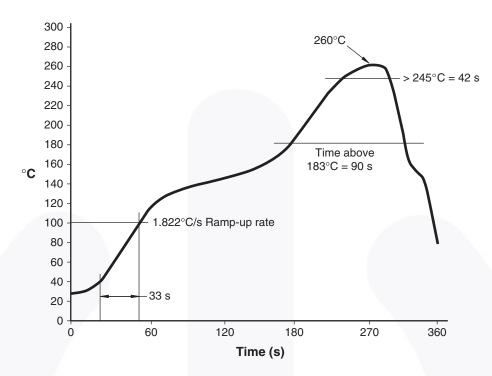


Figure 14. Reflow Profile

Ordering Information

Part Number	Package	Packing Method
H11AA1M	DIP 6-Pin	Tube (50 Units)
H11AA1SM	SMT 6-Pin (Lead Bend)	Tube (50 Units)
H11AA1SR2M	SMT 6-Pin (Lead Bend)	Tape and Reel (1000 Units)
H11AA1VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	Tube (50 Units)
H11AA1SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tube (50 Units)
H11AA1SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tape and Reel (1000 Units)
H11AA1TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	Tube (50 Units)

Note:

2. The product orderable part number system listed in this table also applies to the H11AA4M device.

Marking Information

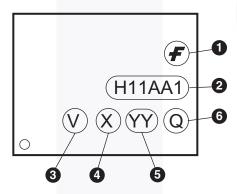
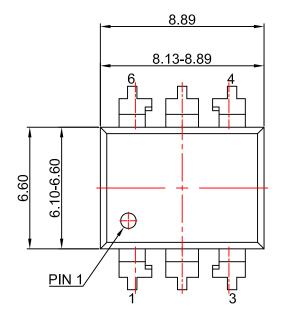
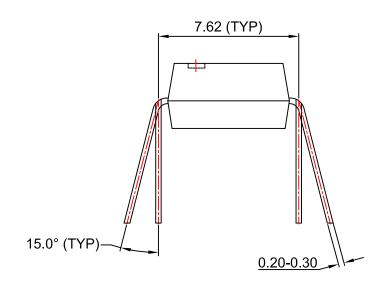


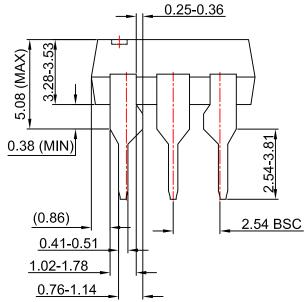
Figure 15. Top Mark

Table 1. Top Mark Definitions

_	
1	Fairchild Logo
2	Device Number
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
4	One-Digit Year Code, e.g., "5"
5	Digit Work Week, Ranging from "01" to "53"
6	Assembly Package Code



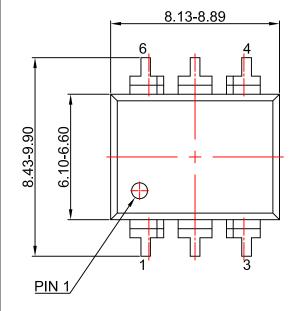


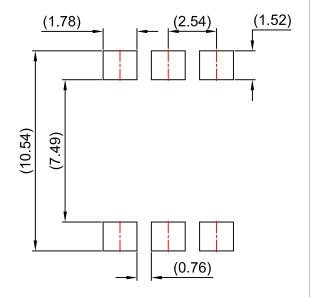


NOTES:

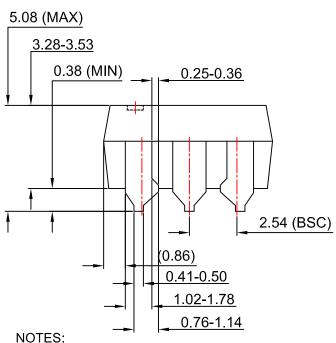
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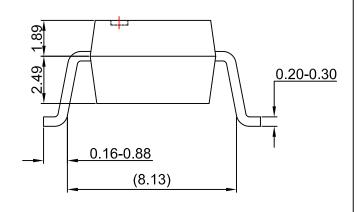






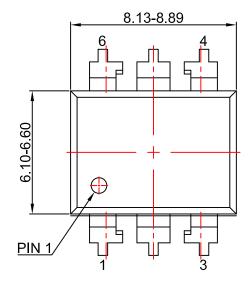
LAND PATTERN RECOMMENDATION

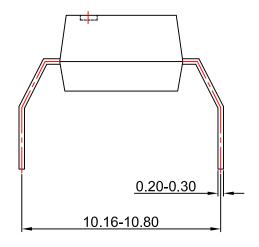


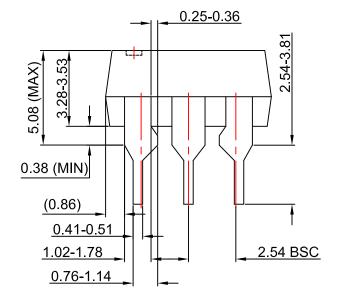


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